

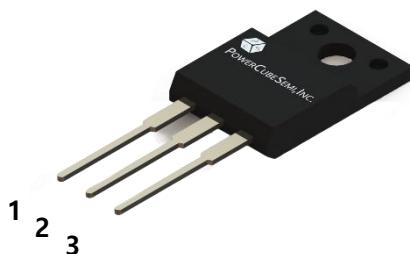
# RTK20N60F

RTK20N60F – 600V 20A N-channel Si Power MOSFET

## Features

- Low  $R_{DS(ON)}$
- Low Gate Charge
- $R_{DS(ON)} (\text{Typ}) = 0.38\Omega$  @  $V_{GS}=10V$
- 100% UIS Tested

Part Number	Package	Note
RTK20N60F	TO-220F	



PKG type : TO-220F

## Applications

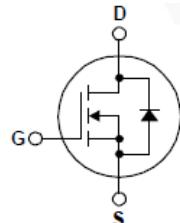
- Power Factor Correction, PFC
- Switched Mode Power Supplies
- LED Driver

## Pin Description

1 : Gate

2 : Drain

3 : Source



## Absolute Maximum Ratings $T_C=25^\circ C$ Unless Otherwise Noted

Symbol	Parameter	Value	Unit
$V_{DSS}$	Drain to Source Voltage	600	V
$V_{GSS}$	Gate to Source Voltage	$\pm 30$	
$I_D$	Continuous Drain Current ( $V_{GS}=10V$ )	$T_C=25^\circ C$	A
		$T_C=100^\circ C$	
$I_{DM}$	Pulsed Drain Current	$T_C=25^\circ C$	A
$P_D$	Power dissipation TO-220F	$T_C=25^\circ C$	W
$dv/dt$	Peak Diode Recovery $dv/dt$	5.0	V/ns
$E_{AS}$	Avalanche Energy, Single Pulsed	720	mJ
$T_J$	Maximum Junction Temperature	-55 to 150	°C
$T_{STG}$	Storage Temperature Range	-55 to 150	°C



## Static Characteristics

T<sub>j</sub>=25°C unless otherwise specified

Symbol	Parameter	Test Condition	Numerical			Unit
			Min	Typ.	Max.	
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> = 0V, I <sub>D</sub> = 250µA	600	-	-	V
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> = 600V, V <sub>GS</sub> = 0V	-	-	10	µA
I <sub>GSS</sub>	Gate-Source Leakage Current	V <sub>GS</sub> =±30V, V <sub>DS</sub> =0V	-	-	±100	nA
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> = 250µA	2	-	4	V
R <sub>DS(ON)</sub>	Static Drain-Source on state resistance	V <sub>GS</sub> = 10V, I <sub>D</sub> = 10A	-	0.38	0.42	Ω

## Dynamic Characteristics

Symbol	Parameter	Test Condition	Numerical			Unit
			Min	Typ.	Max.	
C <sub>iss</sub>	Input capacitance	V <sub>DS</sub> =25V, V <sub>GS</sub> =0V, f=1MHz	-	2962	-	pF
C <sub>oss</sub>	Output capacitance		-	266	-	
C <sub>rss</sub>	Reverse transfer capacitance		-	18	-	
t <sub>d(on)</sub>	Turn-on Delay time	V <sub>DD</sub> =250V, I <sub>D</sub> =20A, V <sub>GS</sub> =0V, R <sub>G</sub> =25Ω	-	20	-	ns
T <sub>r</sub>	Turn-on Rise time		-	50	-	
t <sub>d(off)</sub>	Turn-off Delay time		-	99	-	
T <sub>f</sub>	Turn-off Fall time		-	20	-	

## Gate Charge Characteristics

Symbol	Parameter	Test Condition	Numerical			Unit
			Min	Typ.	Max.	
Q <sub>g(tot)</sub>	Total gate charge at 10V	V <sub>DS</sub> =480V, I <sub>D</sub> =20A, V <sub>GS(on)</sub> =10V	-	58	-	nC
Q <sub>gs</sub>	Gate to source gate charge		-	17	-	
Q <sub>gd</sub>	Gate to drain "Miller" charge		-	19	-	



## Diode Characteristics

Symbol	Parameter	Test Condition	Numerical		Unit
			Typ.	Max.	
$I_{SD}$	Continuous Source Current	$I_{SD}=20A, V_{GS} = 0V$	-	20	A
$I_{SM}$	Pulsed Source Current		-	80	
$V_{SD}$	Drain to source diode forward voltage	$I_{SD}=20A, V_{GS} = 0V$	-	1.4	V
$T_{rr}$	Reverse recovery time	$I_F=20A, V_R=250V, dI_F/dt=100A/\mu s$	500	-	ns
$Q_{rr}$	Reverse recovery charge		7.5	-	$\mu C$
$I_{rrm}$	Reverse recovery current		30.3	-	A

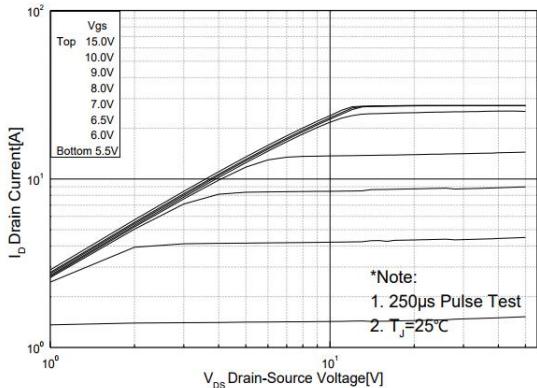
## Thermal Characteristics

Symbol	Parameter	Value	Unit
$R_{\theta JC}$	Thermal Resistance, Junction to Case	2.98	$^{\circ}C/W$
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	110	$^{\circ}C/W$

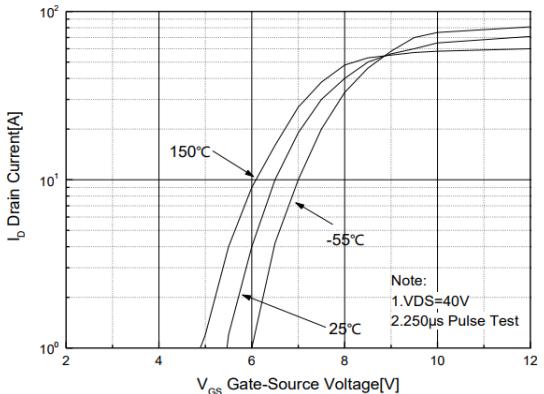
NOTES :

1. Pulse width limited by maximum junction temperature.
2.  $L=10mH, I_{AS}=12A, \text{Starting } T_J=25^{\circ}C$
3.  $I_{SD}=20A, di/dt \leq 100A/\mu s, V_{DD} \leq BV_{DS}, \text{Starting } T_J=25^{\circ}C$

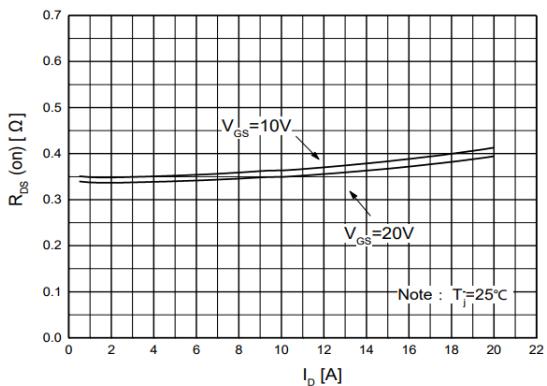
# Typical Characteristics



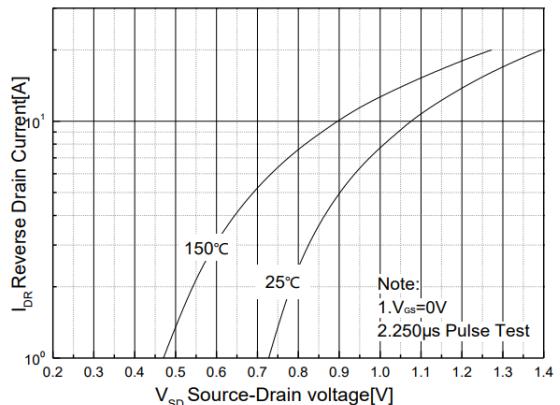
**Figure 1. Output Characteristics**



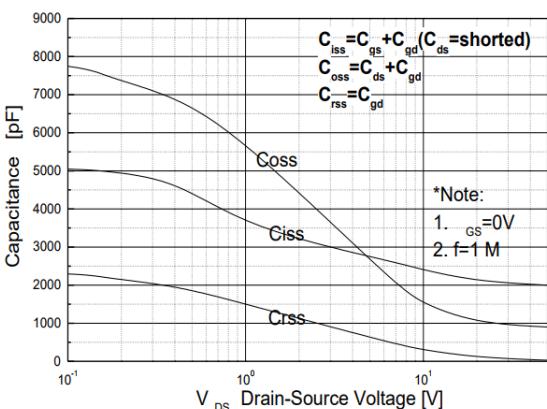
**Figure 2. Transfer Characteristics**



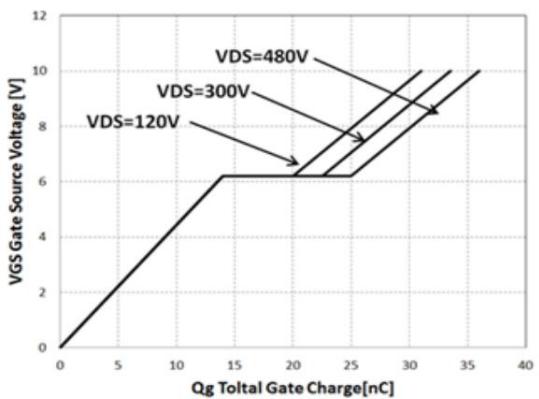
**Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage**



**Figure 4. Typical Source to Drain Diode Forward Voltage**

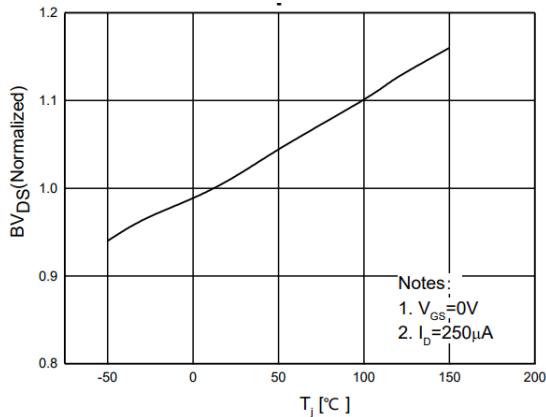


**Figure 5. Capacitance Characteristics**

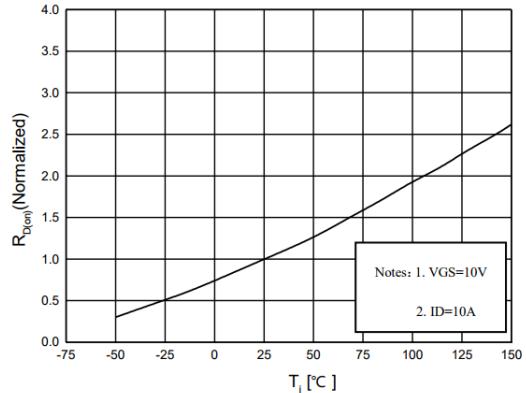


**Figure 6. Gate Charge**

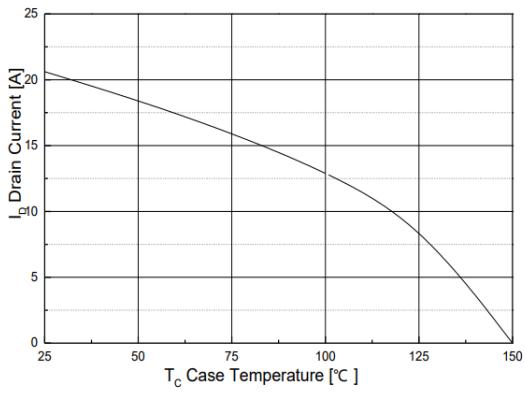
## Typical Characteristics



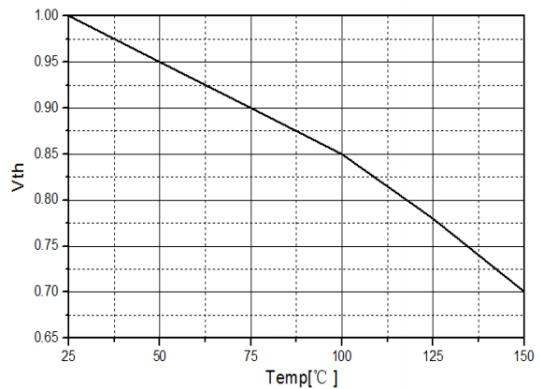
**Figure 7. Breakdown Voltage Variation vs. Temperature**



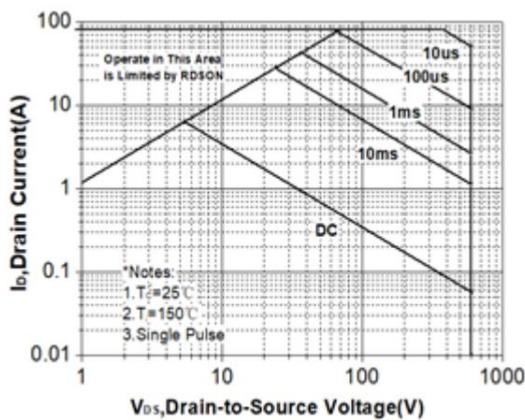
**Figure 8. On-Resistance Variation vs. Temperature**



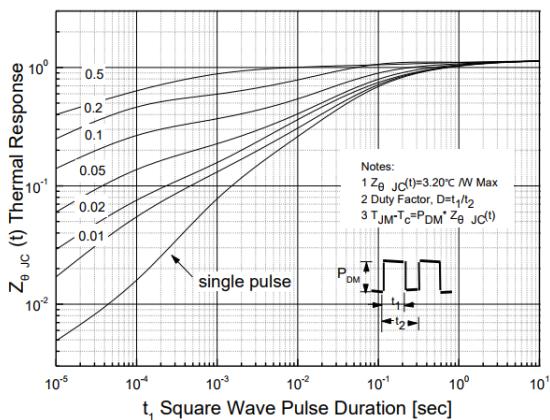
**Figure 9. Maximum Drain Current vs. Case Temperature**



**Figure 10. Gate Threshold Voltage Variation(Normalized) vs. Temperature**

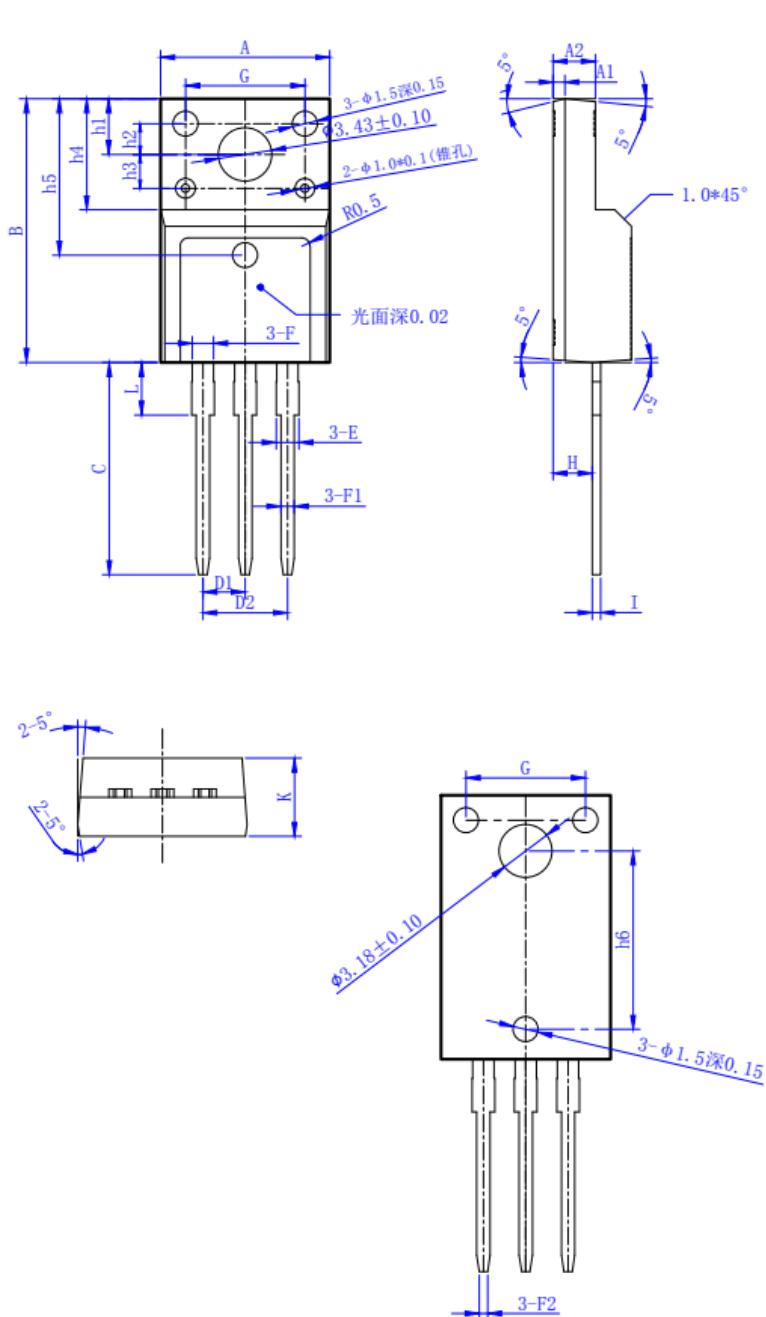


**Figure 11. Maximum Safe Operating Area**



**Figure 12. Transient Thermal Response Curve**

## Package Outline



Unit : mm

SYMBOL	DIMENSIONS		
	MIN	NOM	MAX
<b>A</b>	10.00	10.20	10.40
<b>A1</b>	-	0.70	-
<b>A2</b>	2.35	2.55	2.75
<b>B</b>	15.80	15.90	16.00
<b>C</b>	13.00	13.25	13.50
<b>D1</b>	2.54 BSC		
<b>D2</b>	5.08 BSC		
<b>E</b>	1.27	1.32	1.40
<b>F</b>	1.25	1.28	1.30
<b>F1</b>	0.75	0.80	0.85
<b>F2</b>	0.35	0.40	0.50
<b>G</b>	6.90	7.00	7.10
<b>H</b>	2.66	2.76	2.86
<b>h1</b>	3.20	3.30	3.40
<b>h2</b>	1.70	1.80	1.90
<b>h3</b>	2.00	2.10	2.20
<b>h4</b>	6.70	6.79	6.90
<b>h5</b>	9.30	9.41	9.50
<b>h6</b>	10.44	10.54	10.64
<b>I</b>	0.40	0.50	0.60
<b>K</b>	4.60	4.70	4.80
<b>L</b>	2.90	3.00	3.10